



SCIENCETECH

(3583)

2017/11/29

Safe Harbor Statement



- This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.
- Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.

Sciencetech Corp (3583: TT)



Company Establishment	1979/10/17
IPO	2013/3/12
Capital	NT\$ 811 Million
Chairman	H.L. Hsieh
President	M.T. Hus
Products	Equipment Manufacturing 、 Wafer Reclaim 、 Trading(Agent/Distributor)

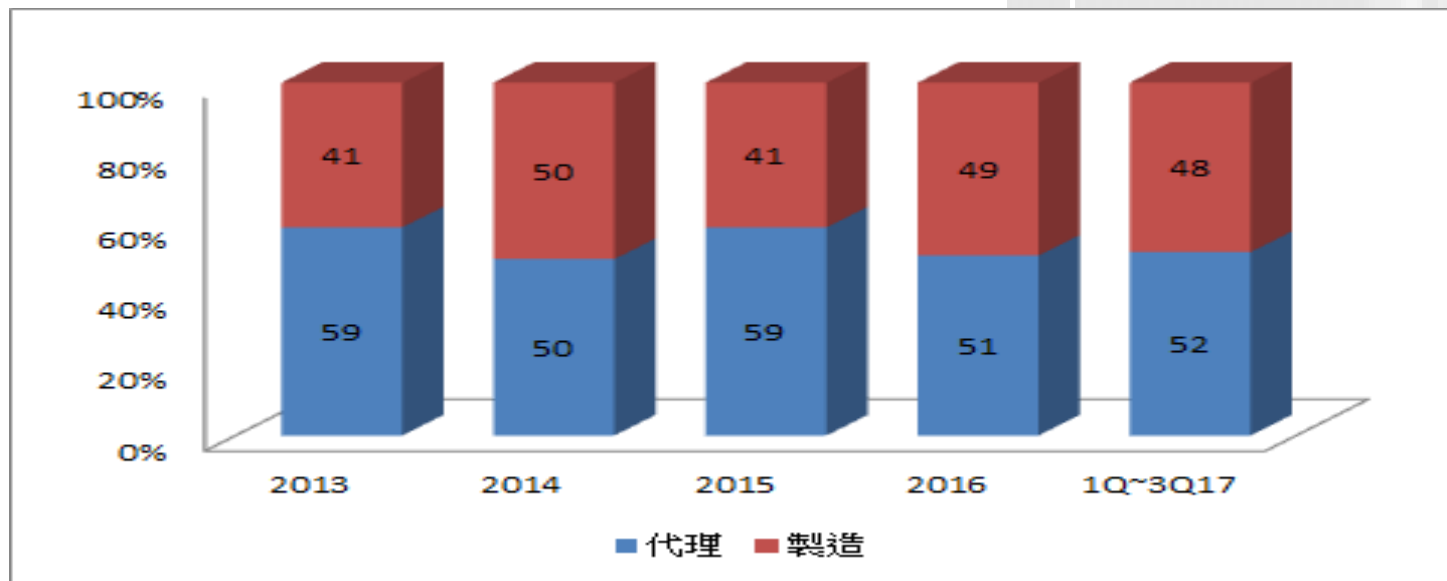
Business
Overviews

Products

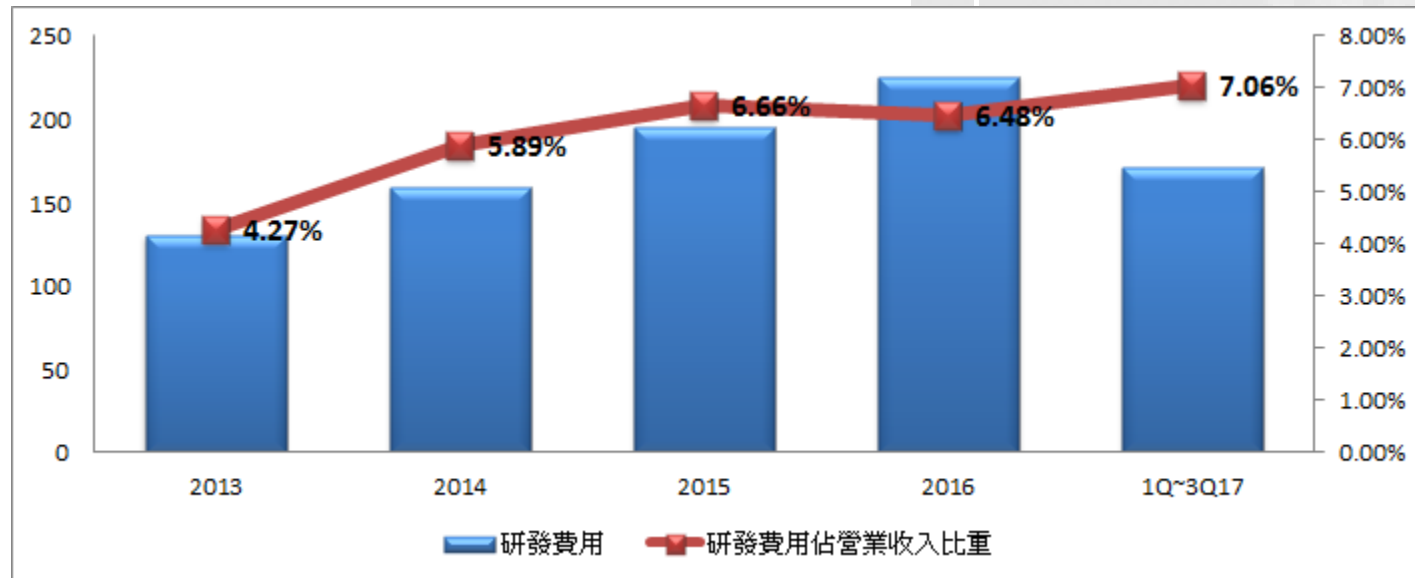
Future
Prospect

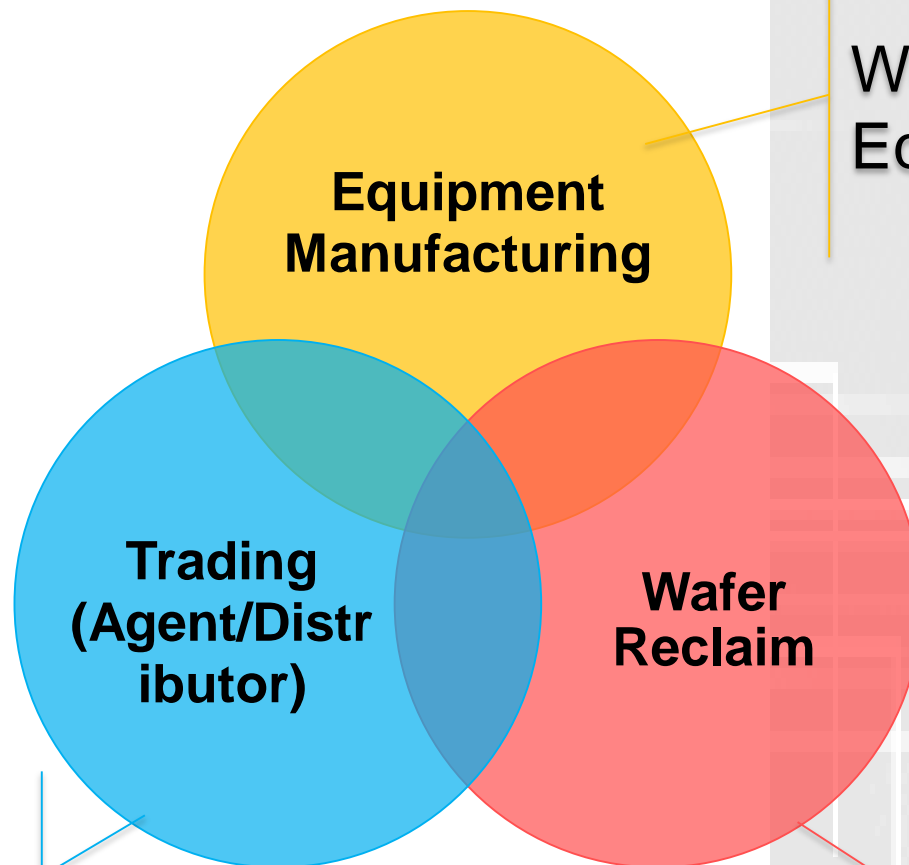
Units : NT \$ M	2013	2014	2015	2016	3Q17	1Q~3Q17
Revenues	3,068	2,717	2,942	3,495	885	2,428
Gross Profit	983	970	903	1,178	335	864
Operating Expenses	629	673	779	835	215	611
Operating Income	354	297	124	343	120	253
Other Income and Expenses	(26)	20	(6)	21	(15)	(26)
Income Before Tax	328	317	119	363	105	227
Net Income	249	246	86	292	86	177
EPS	3.11	3.04	1.06	3.60	1.06	2.18
Gross Margin	32.04%	35.71%	30.69%	33.71%	37.91%	35.60
Operating Margin	11.53%	10.93%	4.23%	9.80%	13.62%	10.44%
Income Before Tax margin	10.69%	11.68%	4.03%	10.40%	11.86%	9.33%

Units : %	2013	2014	2015	2016	1Q~3Q17	Gross Margin
Trading	59	50	59	51	52	Below Average
Manufacturing	41	50	41	49	48	Above Average



Units : NT \$ M	2013	2014	2015	2016	1Q~3Q17
R&D Expenses	131	160	196	226	171
Expenses as % of Revenue	4.27%	5.89%	6.66%	6.48%	7.06%





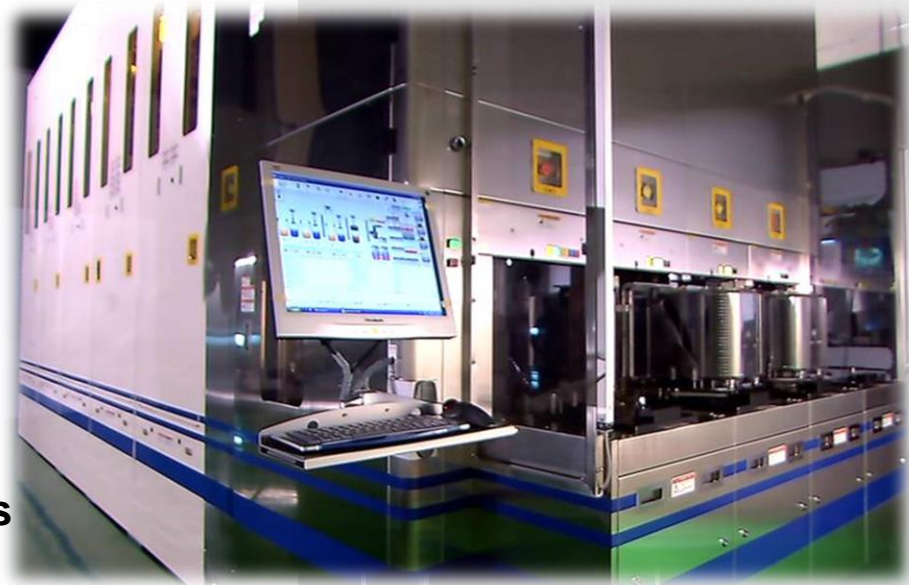
Wet Process
Equipment

Semiconductor and
Optoelectronics
Process Equipment

12" Wafer
Reclaim

Wet process equipment

- **Single wafer/ Batch type**
 - ◆ **8"/12' Advanced packaging**
(Fan-out 、 Solder Bump 、 Copper Pillow 、 Bumping 、 Gold Bump 、 RDL 、 TSV ...ect)
 - ◆ **6"/ 8"/12" Front-end special process** (IoT Sensor 、 Power IC FP sensor 、 RF 、 CMOS 、 Touch Controller 、 MEMS)
 - ◆ **HB LED fully-automatic process**
 - ◆ **MEMS**
 - ◆ **III-V**

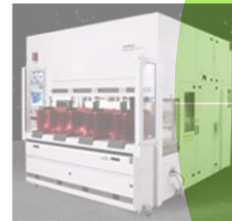


Advanced clean technology
20nm/ 16nm Particle
Low trace metal (<5E9)



Complete particle inspection
(SP1-DLS & SP2)

- 12" Wafer Reclaim
- Capacity: 120K / month
- Separated Cu & Non Cu Line



Cleaning

Etching

**Full Process
Optimization**



Polishing

Grinding

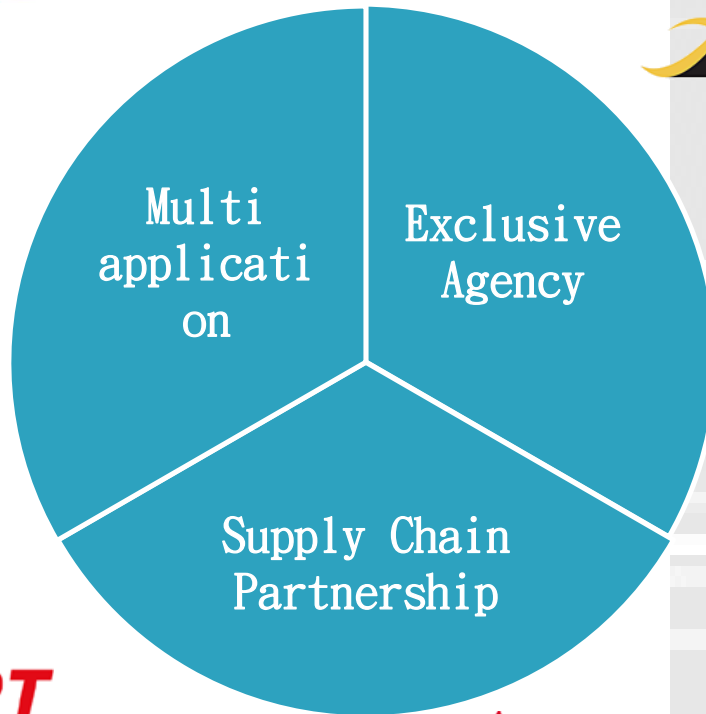
Complete polishing process
Single side polish
Double, side polish
Final Haze polish

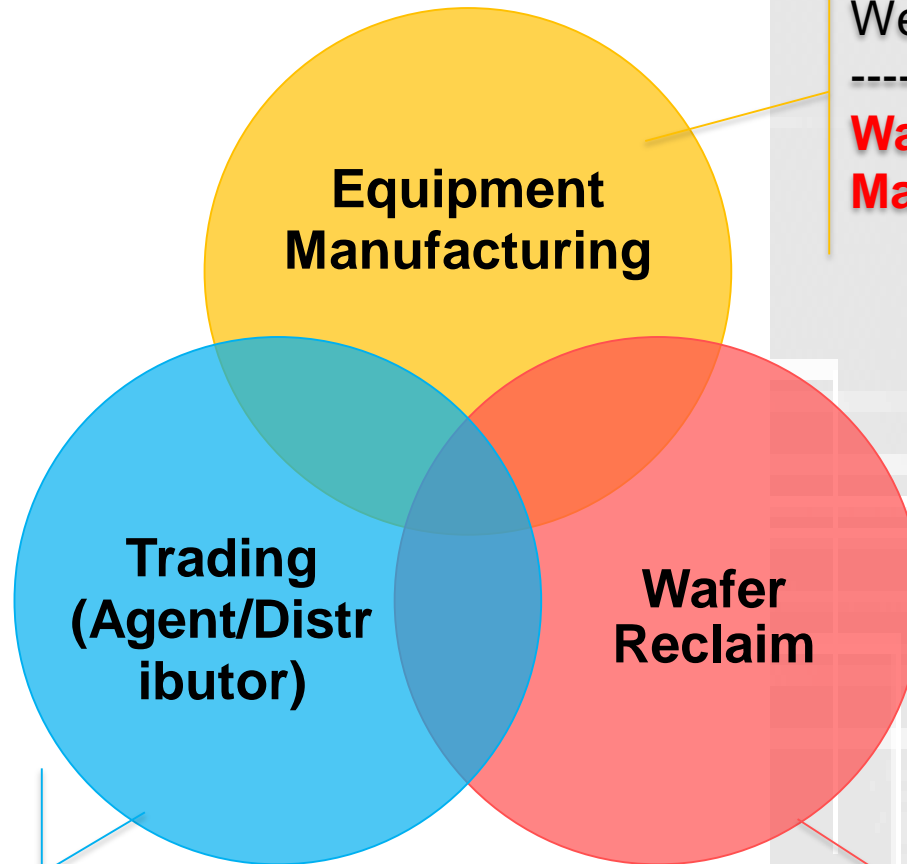


Super flatness
(GBIR<0.5 μ m)

Products

Trading (Agent/Distributor)





Wet Process Equipment

Wafer Support System
Mass Spectrometer

Semiconductor and
Optoelectronics
Process Equipment

AMOLED

12" Wafer Reclaim

SiC Wafer Reclaim

Q & A



Thank You!